

JCET Group Optical Modules



AI Overview

Yes, JCET Group is actively involved in optical modules through its co-packaged optics (CPO) and optical engine integration solutions. JCET Group, a leading semiconductor assembly and test (OSAT) company, has expanded its capabilities to include optical modules and co-packaged optics (CPO) technologies. Their CPO solutions integrate optical engines, which consist of photonic integrated chips (PICs) and electronic integrated chips (EICs), with ASICs on a single substrate using advanced packaging techniques. This integration enables shorter optical paths, higher bandwidth, improved signal integrity, and optimized thermal management, making it suitable for high-performance computing, data centers, and AI applications. JCET's optical engine packaging includes photodetectors, optical waveguides, high-speed modulators, drivers, and trans-impedance amplifiers, supporting heterogeneous integration and system-level reliability. The company has partnered with multiple customers to provide packaging integration, thermal management, and reliability verification for optical modules, demonstrating its active role in the optical interconnect ecosystem. By leveraging its advanced semiconductor packaging expertise, JCET is positioned to deliver next-generation optical solutions that enhance bandwidth density, reduce latency, and improve energy efficiency compared to conventional pluggable optical modules. This confirms that JCET Group is not only involved in optical modules but is also a key player in the development and integration of highly integrated optical systems.

Article Content

JCET's CPO Solution Accelerates Efficiency and Bandwidth

Mr. Owen Jin, VP of JCET Group and General Manager of the AI & Smart Industry BU, stated: "The transition from pluggable optical modules to highly integrated CPO devices brings

CPO Emerges as the New Sought-After as

As artificial intelligence and high-performance computing workloads continue to grow rapidly, system demand for optical interconnect technologies

JCET Group

The greatest value from doing business with JCET is realized when engaging JCET as a full turnkey solutions provider – including IC design and characterization, wafer bumping, packaging, test, and

JCET Group — Edge AI

In terms of high-density packaging and integration technology, JCET provides a number of industry-leading technologies including high-density mounting SMT capability, laser-assisted bonding (LAB),

JCET Group — Home

About JCET Founded in 1972, JCET Group is the world's leading integrated circuit manufacturing and technology services provider. JCET is a global company that serves the world through our rich

JCET Group — News Detail

Shanghai, China, January 21 — JCET Group today announced a key milestone in co-packaged optics (CPO). The company has delivered customer samples of its silicon photonics engine developed on

JCET Group — Automotive

JCET is also actively promoting the mass production applications of core materials such as ceramic substrates for new energy power module packaging (DBC/DBA/AMB), aluminum wire, aluminum

JCET Group — Power & Energy

In power & energy applications, JCET develops AIGC and Communication base station power modules in close partnership with leading customers. We're expanding capacity for mid-to-high-power devices

China's OSAT leaders Tongfu, JCET advance co

The technology integrates optical engines with switch chips to reduce power consumption and expand bandwidth, positioning it as a core enabler for

JCET Releases 2024 Annual Report, Achieves Record-High Revenue

Business Overview In 2024, JCET leveraged its core applications to strengthen customer loyalty and advance the commercialization of innovative technologies, resulting in record-high annual revenue.

JCET Delivers Silicon Photonics Engine Samples,

Shanghai, China, January 21, 2026 — JCET Group today announced a key milestone in co-packaged optics (CPO). The company has delivered customer

JCET Delivers Silicon Photonics Engine Samples,

The samples have successfully completed customer validation testing. The rapid expansion of artificial intelligence and high-performance

JCET (company)

JCET Group is a publicly traded company headquartered in Jiangyin on China's eastern coast. It is the largest Outsourced Semiconductor Assembly and Test (OSAT) company in mainland China and

JCET Group — News Detail

With decades of expertise in power device packaging and testing, JCET Group offers a comprehensive power product portfolio encompassing IGBT, SiC, GaN, and more. In the field of high-density power

JCET (company)

JCET was formed in 1972, when Jiangyin converted a local factory to produce transistors. JCET went public on the Shanghai Stock Exchange in 2003 and continued to grow over time. JCET provides a

Global Advanced Chip Packaging Market (2025-2035)

On 18 February 2025, JCET Group Co. Ltd., which is a Chinese semiconductor outsourced assembly and test company headquartered in

JCET's Co-Packaged Optics: Enabling Next-Gen Performance

By integrating optical engines with ASICs in a single package, we achieve shorter optical paths, optimized thermal management, and reliable system-level performance.

JCET Group — News Detail

Mr. Owen Jin, VP of JCET Group and General Manager of the AI & Smart Industry BU, stated: "The transition from pluggable optical modules to highly integrated CPO devices brings significant system

JCET Group — Company Information

About JCET JCET Group is a global leader in integrated circuit back-end manufacturing and technology services. We provide comprehensive turnkey solutions, including semiconductor package integration

Does JCET Group count as an optical module

Does JCET Group count as an optical module JCET was formed in 1972, when Jiangyin converted a local factory to produce transistors. JCET went public on the Shanghai Stock Exchange in 2003 and

JCET Group — News

JCET CEO Li Zheng Addresses the 30th World Semiconductor Council Meeting
Company News 2026-06-09 JCET Launches Next-Generation Power Module Packaging and Test Solutions for AI Data

JCET powers smart glasses with advanced packaging

Each module comes with unique technical requirements and demands highly specialized semiconductor packaging and testing solutions. At JCET, we bring it all together.

MEMS & Sensors Packaging Trends: 2025-2034 Growth Outlook

JCET Group: A top-tier OSAT, JCET Group provides a full suite of advanced packaging and test services, including specialized solutions for MEMS, leveraging extensive R&D in areas like

JCET's Co-Packaged Optics: Enabling Next-Gen Performance

Driving the Future of Data Connectivity with Co-Packaged Optics (CPO) JCET's latest CPO packaging solutions deliver higher bandwidth, lower power, and improved signal integrity — enabling next ...

JCET Group — Home

JCET provides customers with a full suite of test platforms and engineering services to support a broad range of mixed signal, Radio Frequency (RF), analog, and high-performance digital semiconductor

JCET Group — News Detail

To address this, JCET offers multiple packaging integration solutions for optical engines and flexible layout options for PICs and EICs, while supporting customers in high-speed signal

Contact Us

For more information, pricing, or custom solutions, please contact us:

Website: <https://www.tomor.eu>

Email: info@tomor.eu

Phone: +49 69 2381 5497

Address: Am Hauptbahnhof 10, 60329 Frankfurt am Main, Germany

This document is for informational purposes only. Specifications subject to change without notice.

